

### AMENDMENTS

Please amend claim 5 in the following manner:

Claim 5 (Amended) A process for joining at least two individual substrates, said process comprising:

- (I) applying an adhesive composition as claimed in claim 1 to at least one surface of at least one of the individual substrates;
- (II) mounting another individual substrate to the adhesive treated side of the substrate of (I) to form a laminate thereof;
- (III) applying pressure to the laminate to disperse the adhesive therebetween until each of the substrates contact the largest [organic] inorganic insulator particles of the adhesive composition, and thereafter,
- (IV) curing the adhesive composition.

Respectfully submitted,



Robert L. McKellar  
Reg. No. 26,002  
(989) 631-4551